


CUP-SHAPED PLATING DEVICE

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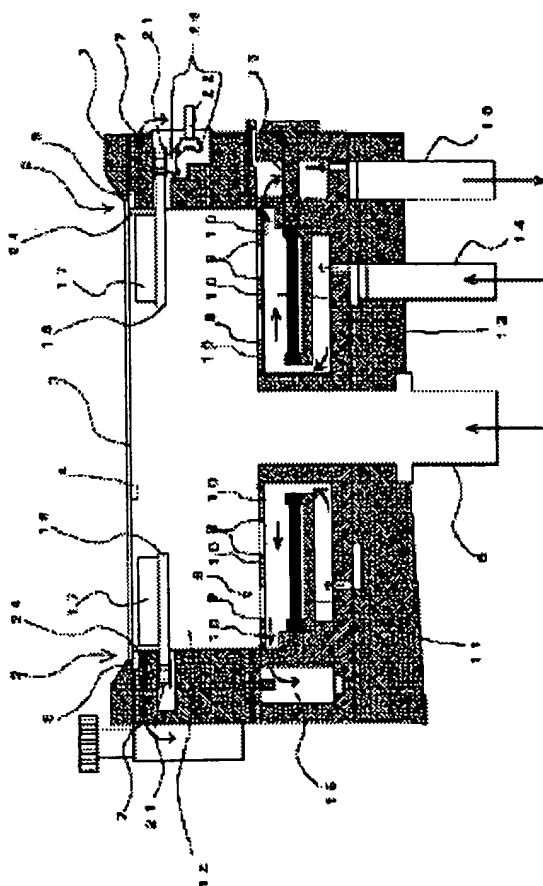
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Abstract of JP2001064795

PROBLEM TO BE SOLVED: To provide a technology to implement a more uniform plating over the whole surface to be plated by improving the non-uniform plating around the surface to be plated caused by the flowing condition of the plating solution in a conventional cup-shaped plating device.

SOLUTION: The cup-shaped plating device comprising a wafer support part 2 formed along an upper opening of a plating tank 1, a solution outflow passage 7 disposed on a lower position of the wafer support part 2, and a solution feed pipe 6 disposed on a bottom part of the plating tank 1, which implements the plating by forming a flow flowing outside the plating tank 1 from the solution outflow passage 7 in the plating solution fed from the solution feed pipe 6 in the rising flow, and bringing a surface 4 to be plated of a wafer 3 placed on the support part in contact with the plating solution, stirring means 17, 18 to forcibly stir the plating solution to be fed in the plating tank 1 are provided on a lower part of the surface 4 to be plated of the placed wafer 3.



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